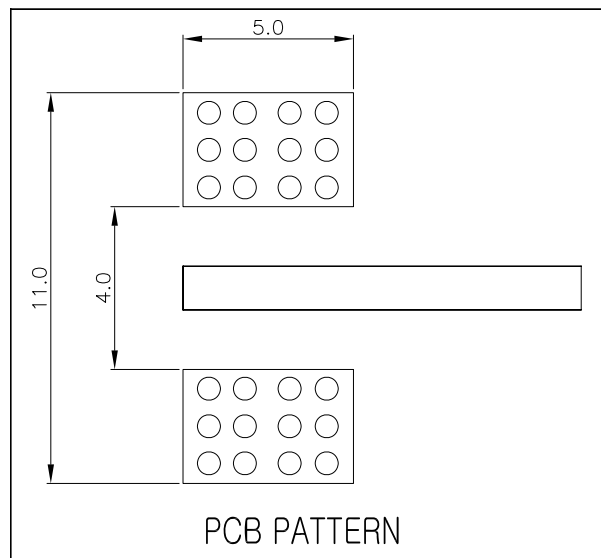
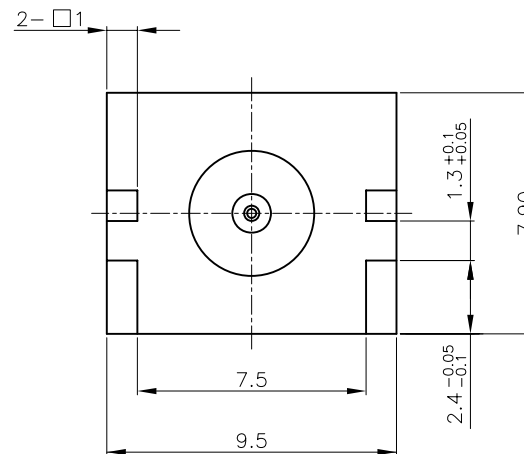
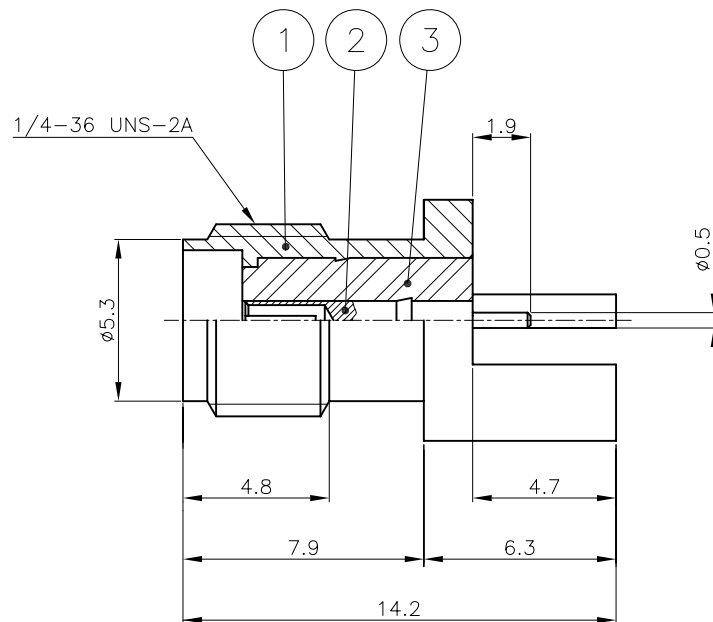


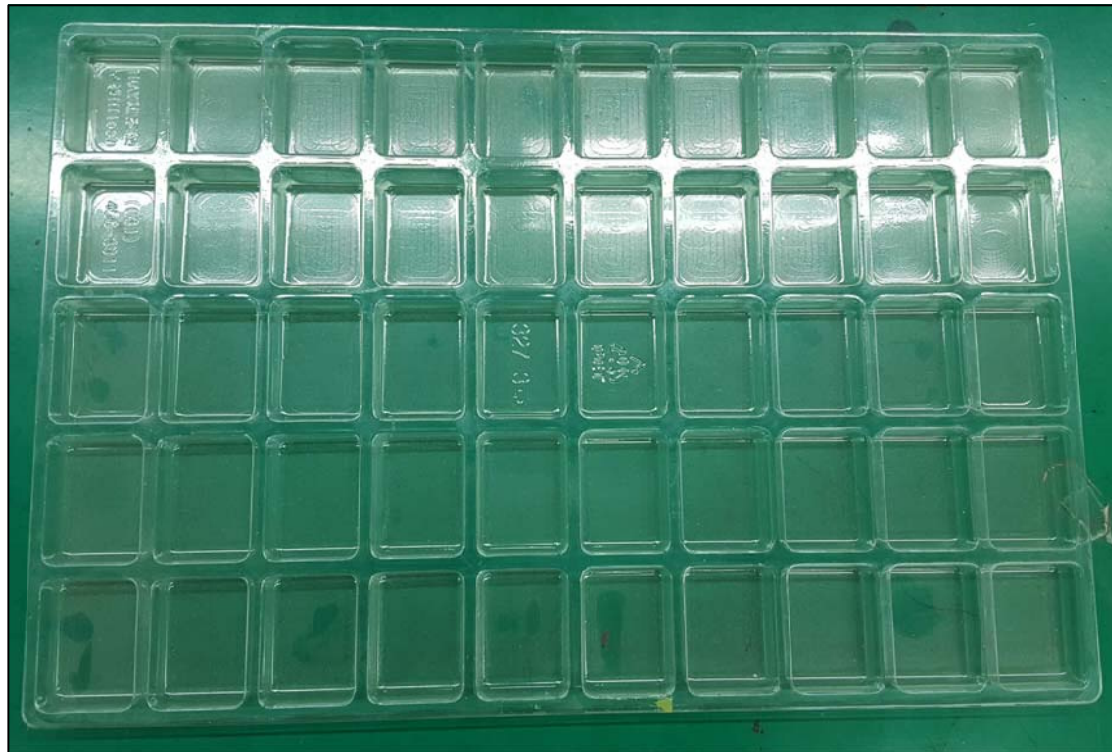
포장사양 2페이지 참조



REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2013.04.29.

3	INSULATOR	1	TEFLON		DIN02177-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02793-5/1
1	BODY	1	MBsBD	Gold Plate	DBD03282-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2013. 04. 29.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	E.H.KIM	KJ COMTECH CO.,LTD. TITLE SMA50 PCB JS-4R (edge)
		DRAWN BY	I.C.KIM	
FINISH		SCALE	4/1	DWG NO. CN02066-7/3 REVISION I R SHEET 1 of 1
		UNIT	mm	



CN02066 포장 사양

1. 부광하이텍 327-3호 (PET) Tray 사용
2. Tray 개당 제품 2ea씩 포장하여
Total 100ea 포장